Session Title:	[TC2] Advanced Cu and Mo CMP
Session Date:	November 21 (Tue.), 2023
Session Time:	10:20-11:50
Session Room:	Room C (Grand Ballroom 2, 2F)
Session Chair:	Prof. Haedo Jeong (Pusan Nat'l Univ., Korea)

[TC2-1] [Invited] 10:20-10:50

Achieving Erosion-Less Depending on Pattern Density via Radical Oxidation in Copper-Film Chemical–Mechanical Planarization

Seong-In Kim, Jin-Woong Cho, Seon-Hwa Kang (Hanyang Univ., Korea), Jin-Hyung Park (ENF Tech. Inc., Korea), and Jea-Gun Park (Hanyang Univ., Korea)

[TC2-2] 10:50-11:10

Electrochemical Galvanic Corrosion Behavior of the Cu/Ru Bimetallic System in the Chemical Mechanical Planarization

Ganggyu Lee, Sungmin Kim, Donghwan Kim, Myungju Woo, Yeram Lee, Hongjun Park, Bobae Lee, Taeseup Song, and Ungyu Paik (Hanyang Univ., Korea)

[TC2-3] 11:10-11:30

CMP Strategy for Dishing Control of TGV Interposers

Seunghun Jeong, Yeongil Shin, Jongmin Jeong, Seonho Jeong, and Haedo Jeong (Pusan Nat'l Univ., Korea)

[TC2-4] 11:30-11:50

Investigation and Characterization of Mo Surface during Mo Post-CMP Cleaning Process

Nayoung Kang, Palwasha Jalalzai, Sumit Kumar, Tae-Gon Kim, and Jin-Goo Park (Hanyang Univ., Korea)